

10/034,221

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APPLICANT: Seung Ho FYISERIAL NO: 10/034,221

WWP: rts

FILED: 12-28-01TITLE: METHOD FOR FABRICATING A SEMICONDUCTOR
EPITAXIAL WAFER HAVING DOPED COARBON AND A SEMI
CONDUCTOR EPITAXIAL WAFERDOCKET CU-2755 DATE: 8-29-03

Mitchell

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